

ABSTRACT OF THE DISCLOSURE

The present invention aims to improve the working efficiency by simplify the mounting operation of an electronic component to a circuit 5 substrate and to increase an adhesive force of the electronic component to prevent inferior production. In the present invention, a chip cover of an insulative property and having a radiating portion has a housing portion on its lower surface. A flip chip piece, which has an electrode surface on which a plurality of projected electrodes of a semiconductor are arranged 10 on its back surface, is accepted to the housing portion. An anisotropic conductive adhesive agent is applied or printed to the electrode surface of the chip piece to embed the projected electrodes, and an insulative adhesive agent is applied or printed in a thicker configuration to an bonding surface which is provided on a lower surface of the chip cover and 15 around the chip piece to embed the projected electrodes. The anisotropic conductive adhesive agent and the insulative adhesive agent are heat-pressed to be temporarily cured.